

**IN THE CLAIMS:**

1. (Original) A method of manufacturing a layered silicone composite material comprising the steps of:

applying a second addition-curable organopolysiloxane composition that contains a second adhesion promoter onto a first silicone layer that is formed by curing a first addition-curable organopolysiloxane composition containing a first adhesion promoter and where the first silicone layer has a hardness of less than JIS A 50; and

forming a second silicone layer that has a hardness of JIS A 50 or more by curing said second addition-curable organopolysiloxane composition.

2. (Original) A method of manufacturing a layered silicone composite material comprising the steps of:

applying a first addition-curable organopolysiloxane composition that contains a first adhesion promoter onto a second silicone layer that is formed by curing a second addition-curable organopolysiloxane composition containing a second adhesion promoter and where the second silicone layer has a hardness of JIS A 50 or more; and

forming a first silicone layer that has a hardness of less than JIS A 50 by curing said first addition-curable organopolysiloxane composition.

3. (Currently Amended) The method according to ~~Claims 1 or 2~~ Claim 1, where at least one of the first adhesion promoter and the second adhesion promoter is an organosilicon compound containing, per molecule, at least one alkoxy group, at least one alkoxylalkoxy group, or both.

4. (Currently Amended) The method according to Claim 3, where at least one of the first adhesion promoter and the second adhesion promoter contains at least one silicon-bonded alkenyl group, at least one silicon-bonded hydrogen atom, or both.
5. (Currently Amended) The method according to ~~Claims 3 or 4~~ Claim 3, where at least one of the first adhesion promoter and the second adhesion promoter contains at least one epoxy group.
6. (Currently Amended) The method according to ~~any of Claims 1 to 5~~ Claim 1, where at least one of the first addition-curable organopolysiloxane composition and the second addition-curable organopolysiloxane composition is free of inorganic filler.
7. (Currently Amended) The method according to any of ~~Claims 1 to 6~~ Claim 1, where the layered silicone composite material is an optically transparent material.
8. (Currently Amended) The method according to any of ~~Claims 1 to 7~~ Claim 1, where layered silicone composite material is at least a part of an optical element.

Please add the following new claims.

9. (New) The method according to Claim 4, where at least one of the first adhesion promoter and the second adhesion promoter contains at least one epoxy group.
10. (New) The method according to Claim 2, where at least one of the first adhesion promoter and the second adhesion promoter is an organosilicon compound containing, per molecule, at least one alkoxy group, at least one alkoxyalkoxy group, or both.

11. (New) The method according to Claim 10, where at least one of the first adhesion promoter and the second adhesion promoter contains at least one silicon-bonded alkenyl group, at least one silicon-bonded hydrogen atom, or both.
12. (New) The method according to Claim 10, where at least one of the first adhesion promoter and the second adhesion promoter contains at least one epoxy group.
13. (New) The method according to Claim 2, where at least one of the first addition-curable organopolysiloxane composition and the second addition-curable organopolysiloxane composition is free of inorganic filler.
14. (New) The method according to any of Claim 2, where the layered silicone composite material is an optically transparent material.
15. (New) The method according to any of Claim 2, where layered silicone composite material is at least a part of an optical element.
16. (New) The method according to Claim 11, where at least one of the first adhesion promoter and the second adhesion promoter contains at least one epoxy group.